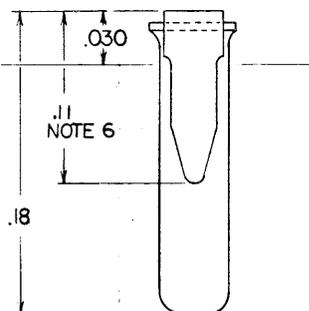
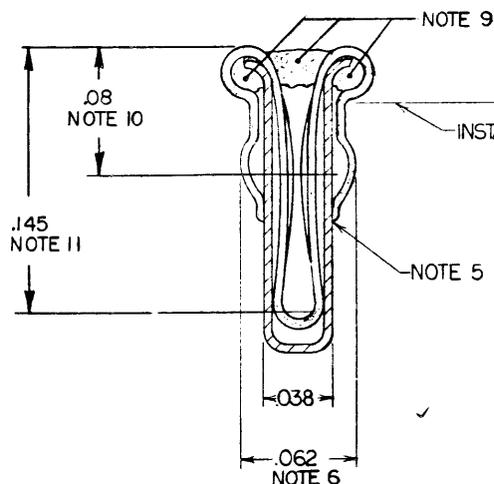
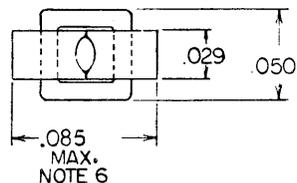


PRODUCT NO.	NOTE
75315-001	As Shown

REVISIONS			
REV	DESCRIPTION	BY	DATE
F	REDRAWN	DEW	7-9-77
G	ADDED NOTE 10	DCH	11-1-77
H	ADD P/N -002	TE	4-30-80
J	DELETED-002, ADDED DIM'S .08 +.145, REVISED NOTES 1,3,4,5,8, & 10. ADDED NOTE 11, DELETED DIMPLE ON DWG	DA	1-25-80
K	SPRING WIDTH .085 WAS .080	BM	9/15/84



NOTES:

- THE SOCKET ASSY SHALL BE SELF RETAINING DURING WAVE SOLDERING IN HOLES FROM .050 TO .058 DIA.
- THE SPRING SHALL SOLDER TO THE CUP DURING WAVE SOLDERING IN SINGLE OR DOUBLE SIDED BOARDS TO 1/16 THK. NO SOLDER SHALL ENTER THE INSIDE OF THE CUP.
- THE SOCKET SHALL ACCEPT ROUND LEADS FROM .012 TO .022 DIA. AND FLAT LEADS WHEN PROPERLY ORIENTED FROM .008 TO .015 THK. BY .020 TO .025 WIDE.
- SEE PRODUCT SPEC 12-006 FOR INSERTION / WITHDRAWAL FORCES.
- GAP BETWEEN SPRING TIPS AND CUP NOT TO EXCEED .003.
- DIMENSIONS APPLY PRIOR TO INSTALLATION
- CUP MATERIAL: GILDING MATERIAL PER MIL.-C-21768. SPRING MATERIAL: B+C_u PER QQ-C-533.
- CUP PLATING: TIN-LEAD 60/40 1,50μ / 60μ THK. SPRING PLATING: 0,76μ / 30μ GOLD (MIL G45204B) TYPE IC, OVER 1,01μ / 40μ NICKEL (QQ-N-290)
- R.T.V. APPLIED TO AREA SHOWN TO PREVENT FLUX AND SOLDER FROM ENTERING SOCKET DURING WAVE SOLDERING.
- SHOWS CENTER LINE OF THEORETICAL POINT OF CONTACT FROM TOP OF SPRING
- SHOWS MAX. DEPTH FOR .020 LEAD FROM TOP OF SPRING

CUSTOMER COPY FOR REFERENCE ONLY

		DO NOT SCALE DRAWING	TOLERANCES UNLESS OTHERWISE NOTED	INCH	MM	DATE	9-9-77
		THIRD ANGLE PROJECTION	LINEAR	.000 ±		NOTE 7	
NEXT ASSY	USED ON	INCH	RADH	.000 ± .008		NOTE 8	
APPLICATION		MM	ANGLES				

BERG ELECTRONICS		
E. I. DU PONT DE NEMOURS & COMPANY		
NEW CUMBERLAND, PA.		
TITLE	MINISERT SOCKET	
SCALE	SIZE	DWG. NO.
3/24/77	X	C 75315
SHEET		1 OF 1